

10V Drive Nch MOSFET

R5019ANX

● Structure

Silicon N-channel MOSFET

● Features

- 1) Low on-resistance.
- 2) Low input capacitance.
- 3) High ESD.

● Application

Switching

● Packaging specifications

| | | |
|----------|------------------------------|------|
| Type | Package | Bulk |
| | Code | - |
| | Basic ordering unit (pieces) | 500 |
| R5019ANX | | ○ |

● Absolute maximum ratings (Ta = 25°C)

| Parameter | Symbol | Limits | Unit | |
|--------------------------------|-------------|-------------|------|---|
| Drain-source voltage | V_{DSS} | 500 | V | |
| Gate-source voltage | V_{GSS} | ±30 | V | |
| Drain current | Continuous | I_D *3 | ±19 | A |
| | Pulsed | I_{DP} *1 | ±76 | A |
| Source current (Body Diode) | Continuous | I_S *3 | 19 | A |
| | Pulsed | I_{SP} *1 | 76 | A |
| Avalanche current | I_{AS} *2 | 9.5 | A | |
| Avalanche energy | E_{AS} *2 | 24.3 | mJ | |
| Power dissipation | P_D *4 | 50 | W | |
| Channel temperature | T_{ch} | 150 | °C | |
| Range of storage temperature | T_{stg} | -55 to +150 | °C | |

*1 $P_w \leq 10 \mu s$, Duty cycle $\leq 1\%$

*2 $L = 500 \mu H$, $V_{DD} = 50V$, $R_G = 25 \Omega$, $T_{ch} = 25^\circ C$

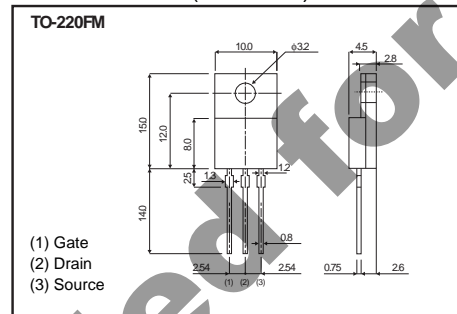
*3 Limited only by maximum temperature allowed.

*4 $T_C = 25^\circ C$

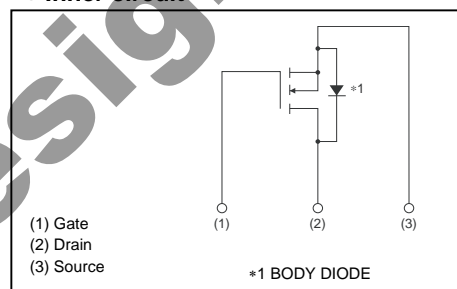
● Thermal resistance

| Parameter | Symbol | Limits | Unit |
|-----------------|----------------|--------|--------|
| Channel to Case | $R_{th(ch-c)}$ | 2.5 | °C / W |

● Dimensions (Unit : mm)



● Inner circuit



●Electrical characteristics (Ta = 25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|---|----------------|------|------|-----------|----------|-----------------------------|
| Gate-source leakage | I_{GSS} | - | - | ± 100 | nA | $V_{GS}=\pm 30V, V_{DS}=0V$ |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | 500 | - | - | V | $I_D=1mA, V_{GS}=0V$ |
| Zero gate voltage drain current | I_{DSS} | - | - | 100 | μA | $V_{DS}=500V, V_{GS}=0V$ |
| Gate threshold voltage | $V_{GS(th)}$ | 2.5 | - | 4.5 | V | $V_{DS}=10V, I_D=1mA$ |
| Static drain-source on-state resistance | $R_{DS(on)}^*$ | - | 0.18 | 0.24 | Ω | $I_D=9.5A, V_{GS}=10V$ |
| Forward transfer admittance | $ Y_{fs} ^*$ | 6.5 | - | - | S | $V_{DS}=10V, I_D=9.5A$ |
| Input capacitance | C_{iss} | - | 2050 | - | pF | $V_{DS}=25V$ |
| Output capacitance | C_{oss} | - | 1200 | - | pF | $V_{GS}=0V$ |
| Reverse transfer capacitance | C_{rss} | - | 50 | - | pF | $f=1MHz$ |
| Turn-on delay time | $t_{d(on)}^*$ | - | 40 | - | ns | $V_{DD}=250V, I_D=9.5A$ |
| Rise time | t_r^* | - | 115 | - | ns | $V_{GS}=10V$ |
| Turn-off delay time | $t_{d(off)}^*$ | - | 165 | - | ns | $R_L=26.3\Omega$ |
| Fall time | t_f^* | - | 100 | - | ns | $R_G=10\Omega$ |
| Total gate charge | Q_g^* | - | 55 | - | nC | $V_{DD}=250V$ |
| Gate-source charge | Q_{gs}^* | - | 10 | - | nC | $I_D=19A$ |
| Gate-drain charge | Q_{gd}^* | - | 24 | - | nC | $V_{GS}=10V$ |

*Pulsed

●Body diode characteristics (Source-Drain)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|-----------------|------------|------|------|------|------|----------------------|
| Forward Voltage | V_{SD}^* | - | - | 1.5 | V | $I_S=19A, V_{GS}=0V$ |

*Pulsed

●Electrical characteristic curves

Fig.1 Typical Output Characteristics (I)

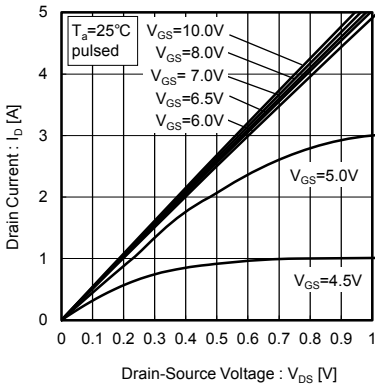


Fig.2 Typical Output Characteristics (II)

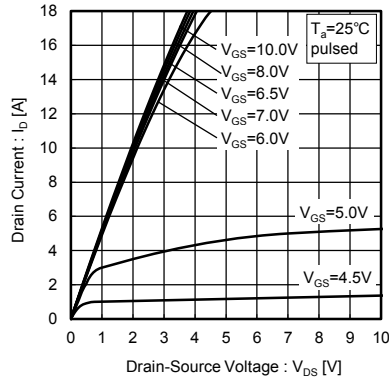


Fig.3 Typical Transfer Characteristics

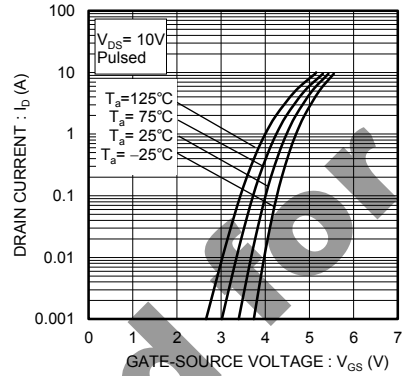


Fig.4 Gate Threshold Voltage vs. Channel Temperature

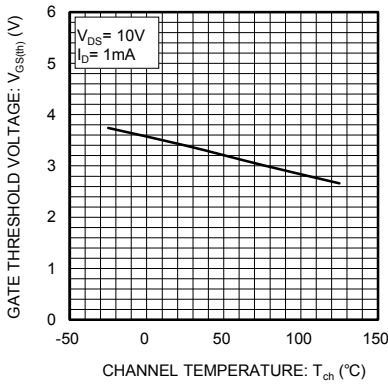


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

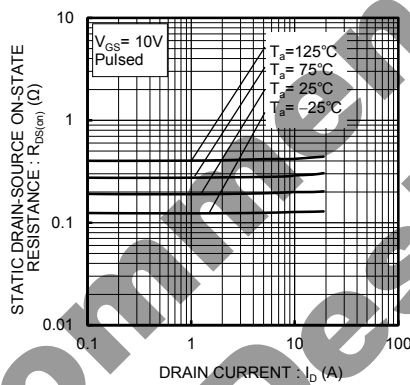


Fig.6 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

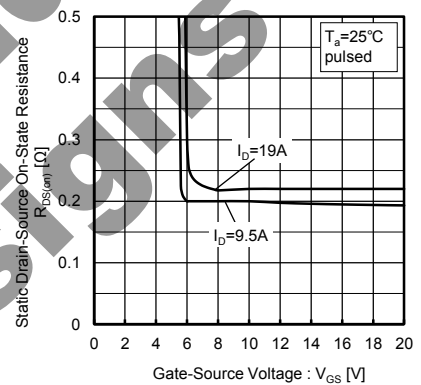


Fig.7 Static Drain-Source On-State Resistance vs. Channel Temperature

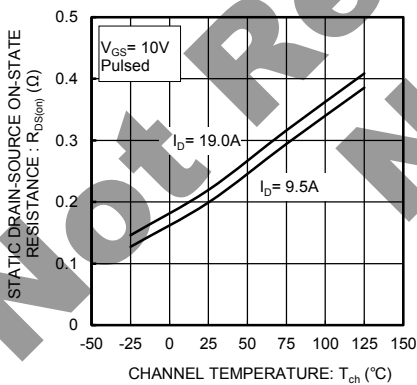


Fig.8 Forward Transfer Admittance vs. Drain Current

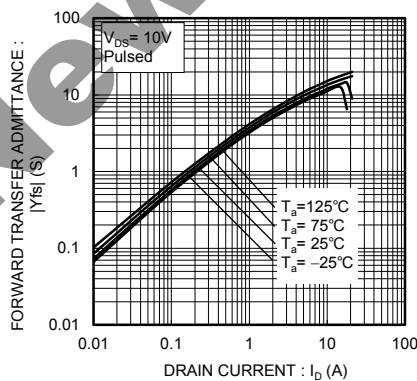


Fig.9 Source Current vs. Source-Drain Voltage

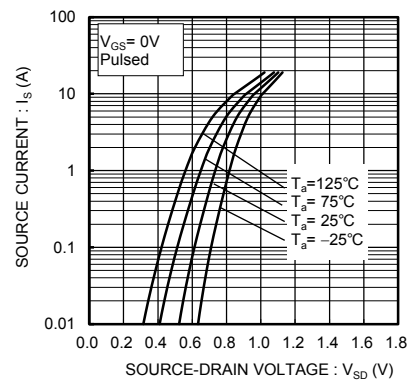


Fig.10 Typical Capacitance vs. Drain-Source Voltage

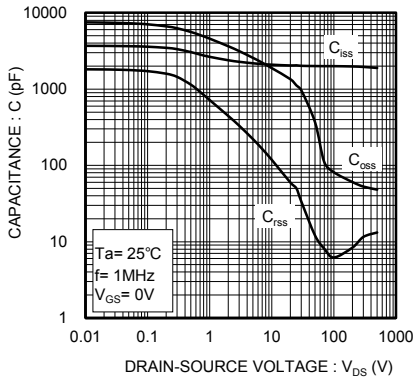


Fig.11 Dynamic Input Characteristics

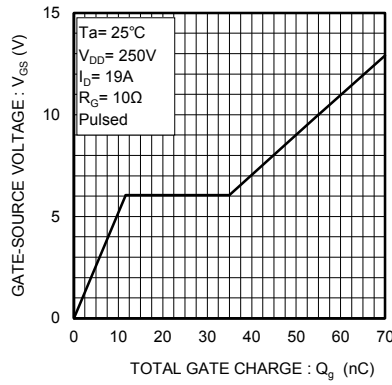


Fig.12 Reverse Recovery Time vs. Source Current

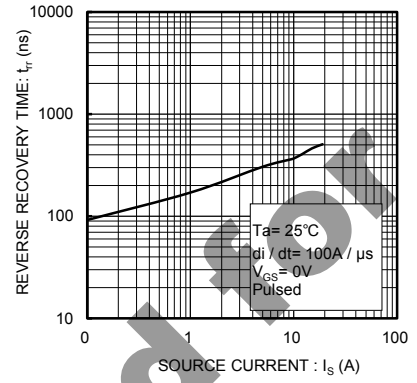
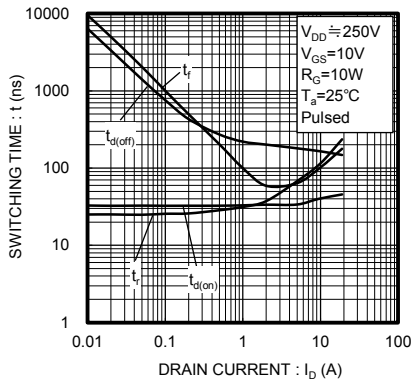


Fig.13 Switching Characteristics



Not Recommended for New Designs

● Measurement circuits

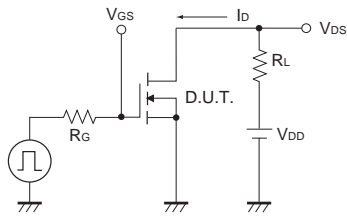


Fig.1-1 Switching Time Measurement Circuit

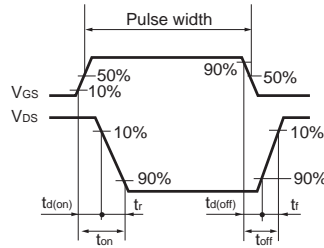


Fig.1-2 Switching Waveforms

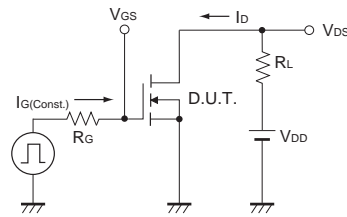


Fig.2-1 Gate Charge Measurement Circuit

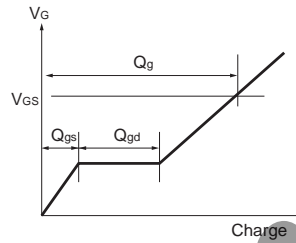


Fig.2-2 Gate Charge Waveform

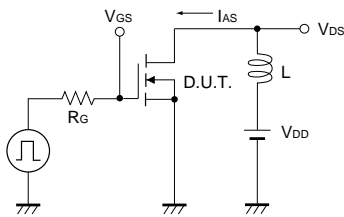


Fig.3-1 Avalanche Measurement Circuit

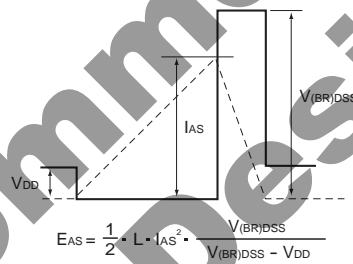


Fig.3-2 Avalanche Waveform

Not Recommended for New Designs

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